

RELIABILITY REPORT
FOR
MAX809ZEXR+T
PLASTIC ENCAPSULATED DEVICES

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MAXIM INTEGRATED PRODUCTS

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Approved by
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Conclusion

The MAX809ZEXR+T successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX803/MAX809/MAX810 are microprocessor (μ P) supervisory circuits used to monitor the power supplies in μ P and digital systems. They provide excellent circuit reliability and low cost by eliminating external components and adjustments when used with +5V, +3.3V, +3.0V, or +2.5V powered circuits. These circuits perform a single function: they assert a reset signal whenever the VCC supply voltage declines below a preset threshold, keeping it asserted for at least 140ms after VCC has risen above the reset threshold. Reset thresholds suitable for operation with a variety of supply voltages are available. The MAX803 has an open-drain output stage, while the MAX809/MAX810 have push-pull outputs. The MAX803's open-drain active-low RESET output requires a pullup resistor that can be connected to a voltage higher than VCC. The MAX803/MAX809 have an active-low RESET output, while the MAX810 has an active-high RESET output. The reset comparator is designed to ignore fast transients on VCC, and the outputs are guaranteed to be in the correct logic state for VCC down to 1V. Low supply current makes the MAX803/MAX809/MAX810 ideal for use in portable equipment. The MAX803 is available in a 3-pin SC70 package, and the MAX809/MAX810 are available in 3-pin SC70 or SOT23 packages.

II. Manufacturing Information

A. Description/Function:	3-Pin Microprocessor Reset Circuits
B. Process:	B8
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Malaysia, Thailand
F. Date of Initial Production:	Pre 1997

III. Packaging Information

A. Package Type:	3L SC70
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Non-conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1601-0080 / A
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	1
J. Single Layer Theta Ja:	340°C/W
K. Single Layer Theta Jc:	115°C/W
L. Multi Layer Theta Ja:	340.4°C/W
M. Multi Layer Theta Jc:	120°C/W

IV. Die Information

A. Dimensions:	30 X 29 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Richard Aburano (Manager, Reliability Engineering)
Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 143 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 7.7 \times 10^{-9}$$

$$\lambda = 7.7 \text{ F.I.T. (60\% confidence level @ 25}^\circ\text{C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the B8 Process results in a FIT Rate of 0.06 @ 25C and 0.99 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot I5QEAQ001F D/C 0002)

The MS39-5 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-150mA.

Table 1
Reliability Evaluation Test Results

MAX809ZEXR+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C	DC Parameters	80	0	I5QEBQ002D, D/C 0106
	Biased	& functionality	63	0	I5QAAQ001F, D/C 9943
	Time = 192 hrs.				

Note 1: Life Test Data may represent plastic DIP qualification lots.